

ABSTRACT

In the present invention, a negative-type photosensitive resin composition containing a bisphenol novolac-type epoxy resin and a cationic polymerization initiator is employed. The bisphenol novolac-type epoxy resin has a weight-average molecular weight of 4000 or greater. Such a negative-type photosensitive resin composition is suitable as a photosensitive material used for forming a top plate portion of a hollow structure (100) including a support (10), a first cover layer (30), and a second cover layer (40) (top plate portion), in which a hollow portion (50) is provided between the support (10) and the first cover layer (30), and a plurality of holes (35) penetrating from the hollow portion (50) to the top plate portion are formed in the first cover layer (30). According to such a negative-type photosensitive resin composition, it is possible to stably form a resin film on the first cover layer (30) having the holes (35) without the negative-type photosensitive resin composition flowing through the holes (35) of the first cover layer (30) and falling into the hollow portion (50) regardless of conditions of a manufacturing process.